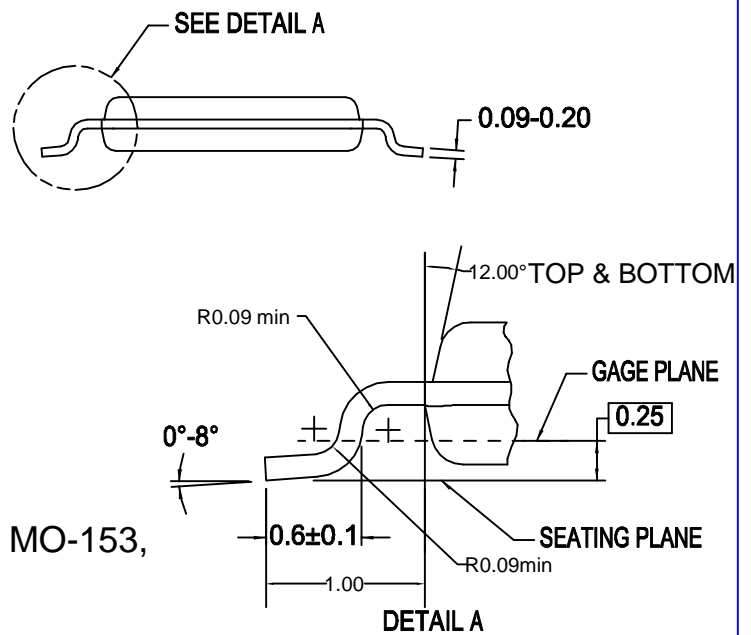
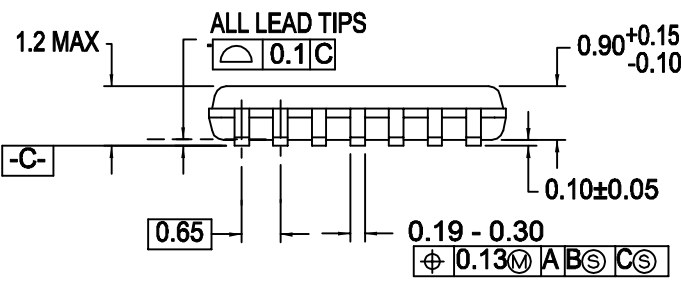
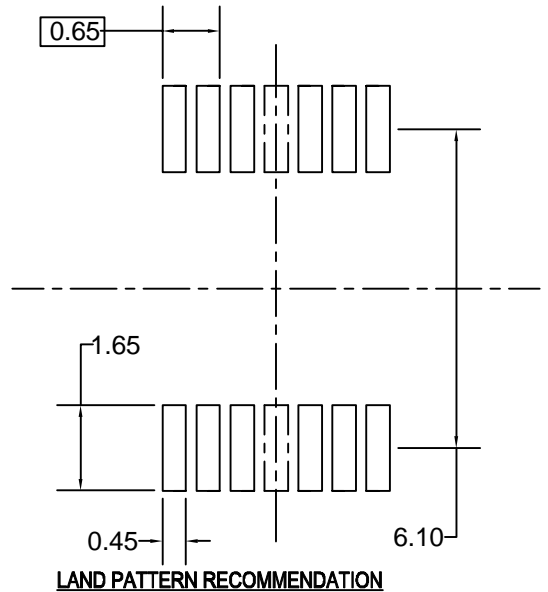
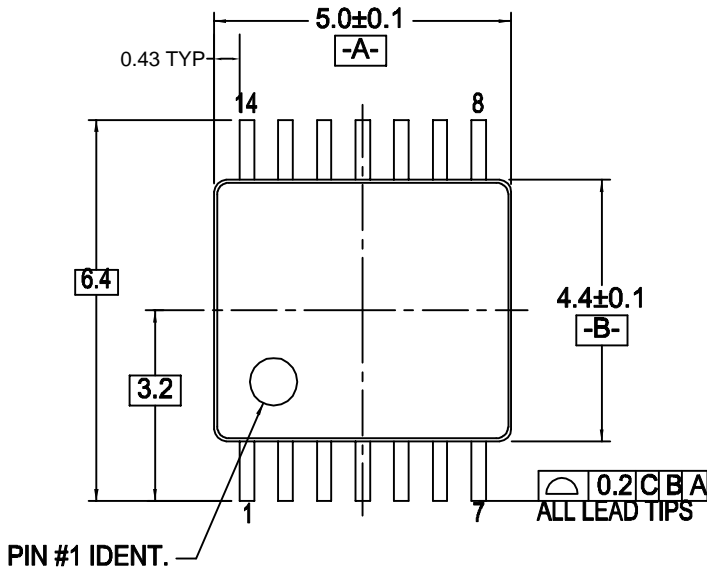


**REVISIONS**

LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
C	REVISE & REDRAW ON PRO/E PER CURRENT STD; CORRECT DET CALLOUT FROM D TO A	11099	08/21/95	MS/
C1	CHANGE TO (FSPM) DRAWING		4-6-98	FEITAN
C2	ADDED NOTES SECTION, ADDED RADIUS DIMS, MOLDED BODY ANGLE DIMS, AND FILENAME		6-12-98	H.ALLEN
C3	CHANGED TITLE, ADDED TITLE		6-23-98	H.ALLEN
D	CHANGED REVISION LEVEL ONLY		11/12/04	H.ALLEN
6	UPDATED LAND PATTERN		9 JULY 07	L.HUEBENER



**NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

<b>APPROVALS</b>		<b>DATE</b>	<b>FAIRCHILD SEMICONDUCTOR™</b>		
DRAWN	L.HUEBENER	9 JULY 07	14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE		
DFTG. CHK.	H.ALLEN	31 JULY 07			
ENGR. CHK.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-MTC14	6
DO NOT SCALE DRAWING				SHEET 1 of 1	